

## NOT RECOMMENDED FOR NEW DESIGN - USE AP7361C



AP7361

1A LOW DROPOUT ADJUSTABLE AND FIXED-MODE REGULATOR WITH ENABLE

OUT

NC

GND

3

4

5 OUT

GN

IN

ADJ/NC

(Top View)

SOT223/SOT223R

(Top View)

(Top View)

GND

U-DFN3030-8

ΟυτΓ

EN 2

NC 3

GND 4

1

IN

NC

FN

6 NC

Top View )

3

T0252/T0252R

(Top View)

SO-8EP

8 IN

7 NC

6 NC

5 NC

**Pin Assignments** 

## Description

The AP7361 is a 1A, adjustable and fixed output voltage, ultra-low dropout linear regulator with enable. The device includes pass element, error amplifier, band-gap reference, current limit and thermal shutdown circuitry. The device is turned on when the EN pin is set to logic high level.

The characteristics of the low dropout voltage and low quiescent current make it suitable for low to medium power applications, for example, laptop computers, audio and video applications, and battery powered devices. The typical quiescent current is approximately 70µA. Built-in current-limit and thermal-shutdown functions prevent IC from damage in fault conditions.

The AP7361 is available in U-DFN3030-8, SOT89-5, SOT223, TO252 and SO-8EP package.

### Features

- Wide input voltage range: 2.2V 6V
- 150mV Very Low Dropout at 300mA Load
- 500mV Very Low Dropout at 1A Load
- Low Quiescent Current (I<sub>Q</sub>): 70µA Typical
- Adjustable Output Voltage Range: 1V to 5.0V
- Fixed Output Options: 1V to 3.3V
- Very-Fast Transient Response
- **High PSRR**
- Accurate Voltage Regulation
- Current Limiting and Short Circuit Protection
- Thermal Shutdown Protection
- Stable with Ceramic Output Capacitor  $\ge 2.2\mu F$
- Ambient Temperature Range -40°C to +85°C
- U-DFN3030-8, SOT89-5, SOT223/SOT223R, TO252/TO252R and SO-8EP
- Available in "Green" Molding Compound (No Br, Sb)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

# Applications

EN 1

GND 2

ADJ/NC 3

- Servers and Laptops
- FPGA and DSP Core or I/O Power

SOT89-5

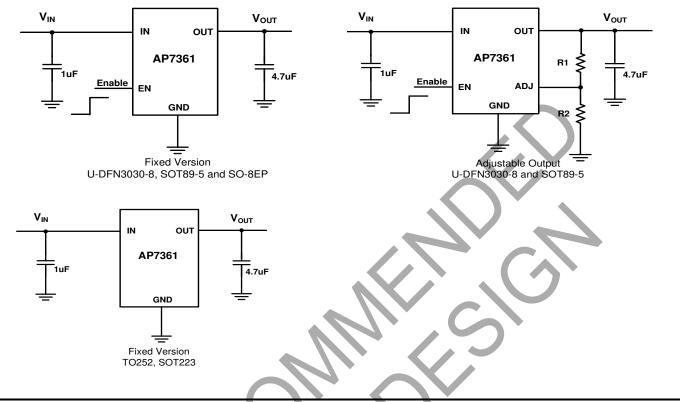
- TV, and Home Electrical Appliances
- **Battery-Powered Devices**
- Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

## and Lead-free

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



# **Typical Applications Circuit**

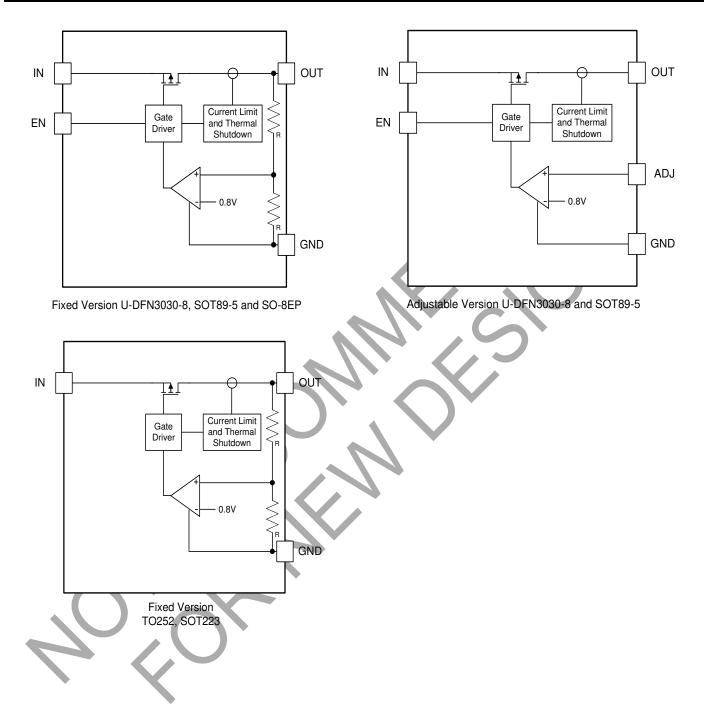


# **Pin Descriptions**

-								
Pin			Pi	n Number				Function
Name	U-DFN3030-8	SOT89-5	TO252	TO252R	SOT223	SOT223R	SO-8EP	Function
IN	8	4	1	3	1	3	8	The input of the regulator. Bypass to ground through at least 1µF ceramic capacitor.
OUT	1	5	3	2	3	2	1	The output of the regulator. Bypass to ground through at least $2.2\mu$ F ceramic capacitor. For improved ac load response a larger capacitor is recommended.
GND	4	2	2	1	2	1	4	Ground
ADJ	3	3	NA	NA	NA	NA	NA	Adjustable voltage version only – a resistor divider from this pin to the OUT pin and ground sets the output voltage.
EN	5	1	NA	NA	NA	NA	2	Enable input, active high
NC	2, 6, 7	NA	NA	NA	NA	NA	3, 5, 6, 7	No connection
	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~							



# **Functional Block Diagram**





Symbol	Paramo	eter	Ratings	Unit	
ESD HBM	Human Body Model ESD Protection	1	> 2	KV	
ESD MM	Machine Model ESD Protection (No	te 5)	> 200	V	
VIN	Input Voltage		6.5	V	
	OUT, ADJ, EN Voltage		V <sub>IN</sub> +0.3	V	
TJ	Operating Junction Temperature Ra	ange	-40 to +150	°C	
T <sub>ST</sub>	Storage Temperature Range		-65 to +150	°C	
PD	Power Dissipation (Note 4)	Power Dissipation (Note 4)			
		U-DFN3030-8	1,700		
		TO252	1,250		
PD	Power Dissipation (Note 4)	SOT223	1,100	mW	
		SOT89-5	800		
		SO-8EP	1,190		

## Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Notes: 4. Ratings apply to ambient temperature at +25°C.

5. ESD MM rating at 150V for EN pin.

Stresses greater than the 'Absolute Maximum Ratings' specified above, may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability may be affected by exposure to absolute maximum rating conditions for extended periods of time.

# Recommended Operating Conditions (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Para	ameter		Min	Max	Unit
V <sub>IN</sub>	Input Voltage			2.2	6.0	V
I <sub>OUT</sub>	Output Current (Note 6)			0	1.0	А
T <sub>A</sub>	Operating Ambient Temperature			-40	+85	°C

Note: 6. The device maintains a stable, regulated output voltage without a load current. When the output current is large, attention should be given to the limitation of the package power dissipation.



Symbol	Parameter	Test Conditions		Тур	Max	Unit
V <sub>REF</sub>	FB Reference Voltage	$I_{OUT} = 10mA, T_A = +25^{\circ}C$		0.8		V
I <sub>ADJ</sub>	ADJ Pin Leakage			0.1	0.5	μΑ
lq	Input Quiescent Current	Enabled, I <sub>OUT</sub> = 0A		70	90	μA
I <sub>SHDN</sub>	Input Shutdown Current	$V_{EN} = 0V, I_{OUT} = 0A$	-1	0.05	1	μA
		$I_{OUT} = 100 \text{mA}, T_{A} = +25^{\circ}\text{C}$	-1		1	
Vout	Output Voltage Accuracy	$I_{OUT} = 100 \text{mA}, -40^{\circ}\text{C} \le T_{A} \le +85^{\circ}\text{C}$	-2		2	%
		Over VIN, IOUT, and TA	-3	±0.5	3	3
Δνουτ	Line Degulation	$V_{IN} = V_{OUT} + 1V$ to $T_A = +25^{\circ}C$		0.01	0.1	o/ \/
ΔVIN× VOUT	Line Regulation	6V, $I_{OUT}$ = 100mA -40°C ≤T <sub>A</sub> ≤ +85°C			0.2	%/V
	Logd Degulation	I <sub>OUT</sub> from 1mA to 300mA	-1.0	0.5	1.0	%
$\Delta V_{OUT}$ / $V_{OUT}$	Load Regulation	I <sub>OUT</sub> from 1mA to 1A	-1.0	0.5	1.0	%
		I <sub>OUT</sub> = 300mA		150	200	
VDROPOUT	Dropout Voltage (Note 7)	I <sub>OUT</sub> = 500mA		250	350	350 mV 700
		I <sub>OUT</sub> = 1A		500	700	
VIL	EN Input Logic Low Voltage				0.3	V
VIH	EN Input Logic High Voltage		1.0		V <sub>IN</sub>	V
I <sub>EN</sub>	EN Input Leakage	$V_{IN} = 6V, V_{EN} = 0V$ or $6V$	-0.1	0.01	0.1	μA
ILIMIT	Current Limit	VIN = VOUT + 1V	1.1	1.5		Α
I <sub>SHORT</sub>	Short-Circuit Current	V <sub>IN</sub> = V <sub>OUT</sub> +1V, Output Voltage < 15% V <sub>OUT</sub>		200		mA
DODD	Power Supply Rejection Ratio	f = 1KHz, I <sub>OUT</sub> = 100mA	60	65		
PSRR	(Note 8)	f = 10KHz, l <sub>OUT</sub> = 100mA		45		dB
tsт	Start-Up Time	$V_{OUT} = 3V$ , $C_{OUT} = 1\mu F$ , $R_L = 30\Omega$		200		μs
Δνουτ				1100		
$\overline{\Delta T_A \times VOUT}$	Output Voltage Temperature Coefficient	$I_{OUT} = 100$ mA, -40°C $\leq T_A \leq +85$ °C		±130		ppm/°C
T <sub>SHDN</sub>	Thermal Shutdown Threshold			150		°C
T <sub>HYS</sub>	Thermal Shutdown Hysteresis			20		°C
		U-DFN3030-8 (Note 9)		70		
		TO252 (Note 9)		95		
θ <sub>JA</sub>	Thermal Resistance Junction-to-Ambient	SOT223 (Note 9)		110		°C/W
		SOT89-5 (Note 9)		150		
		SO-8EP (Note 9)		100		

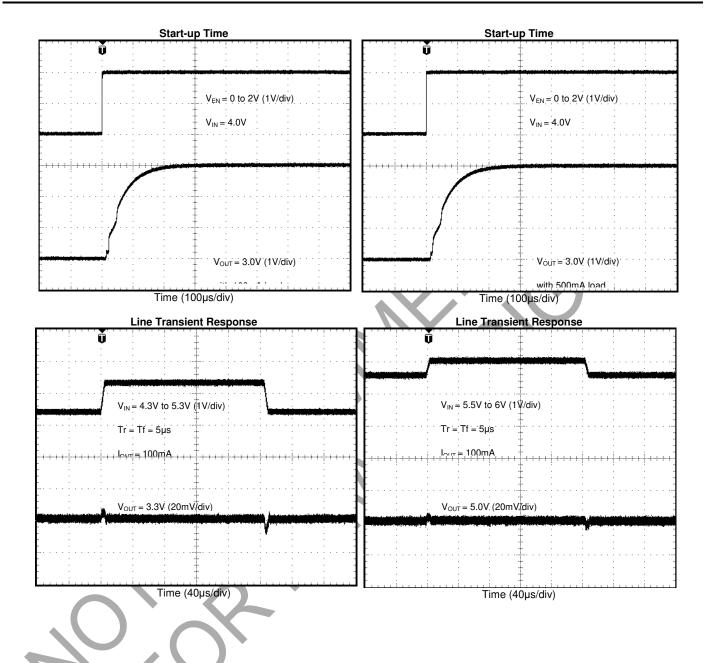
## Electrical Characteristics (@T<sub>A</sub> = +25°C, V<sub>IN</sub> = V<sub>OUT</sub> +1V, C<sub>IN</sub> = 1µF, C<sub>OUT</sub> = 4.7µF, V<sub>EN</sub> = V<sub>IN</sub> unless otherwise specified.)

Notes:

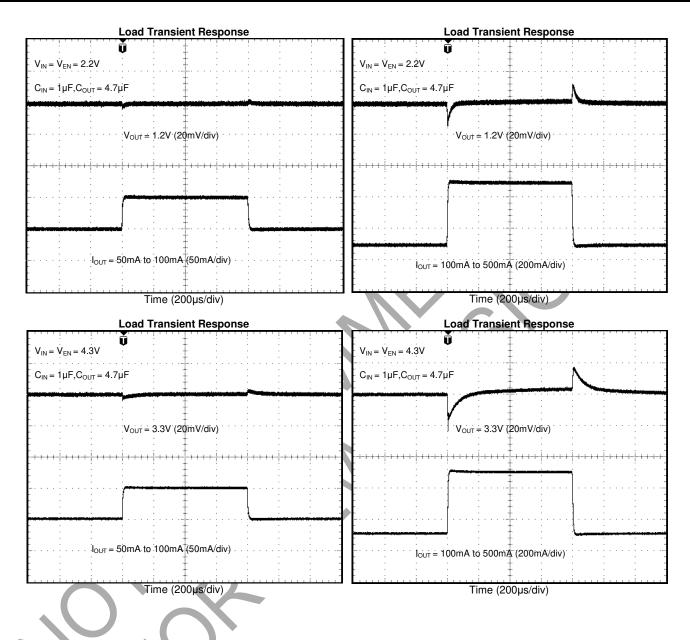
7. Dropout voltage is the voltage difference between the input and the output at which the output voltage drops 2% below its nominal value. This parameter only applies to output voltages above 1.5V since minimum V<sub>IN</sub> = 2.2V.
8. For V<sub>IN</sub> ≥ 2.5V and V<sub>IN</sub> = V<sub>OUT</sub> +1V. For V<sub>IN</sub> < 2.5V, the PSRR performance may be reduced.</li>
9. Test condition: DFN3030E-8, SO-8EP device mounted on 2"x2", FR-4 substrate PCB, with minimum recommended pad on top layer and thermal vias to bottom layer ground plane. TO252 device mounted on 2"x2", FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. SOT223 the device is mounted on FR-4 substrate PC board, with minimum recommended pad layout. SOT89-5L device mounted on 1"x1" FR-4 substrate PC board, with minimum recommended pad layout.



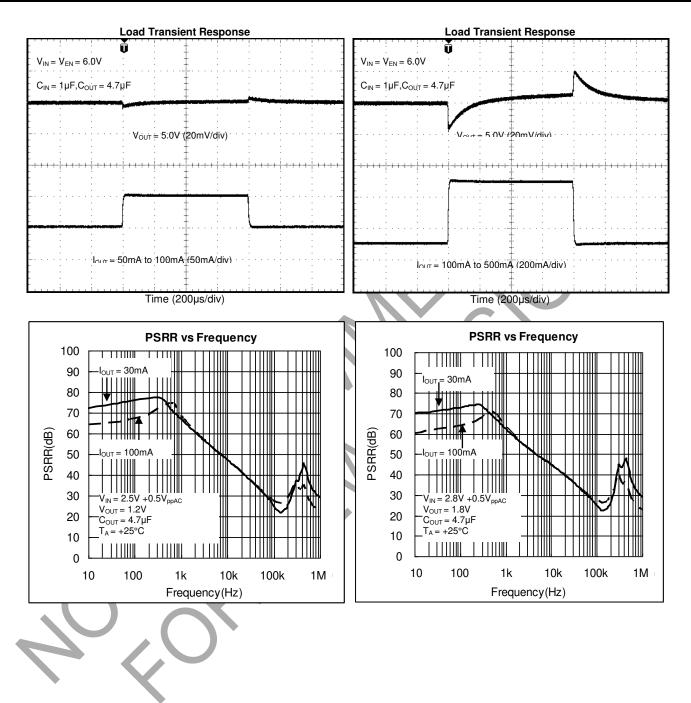
# **Typical Performance Characteristics**



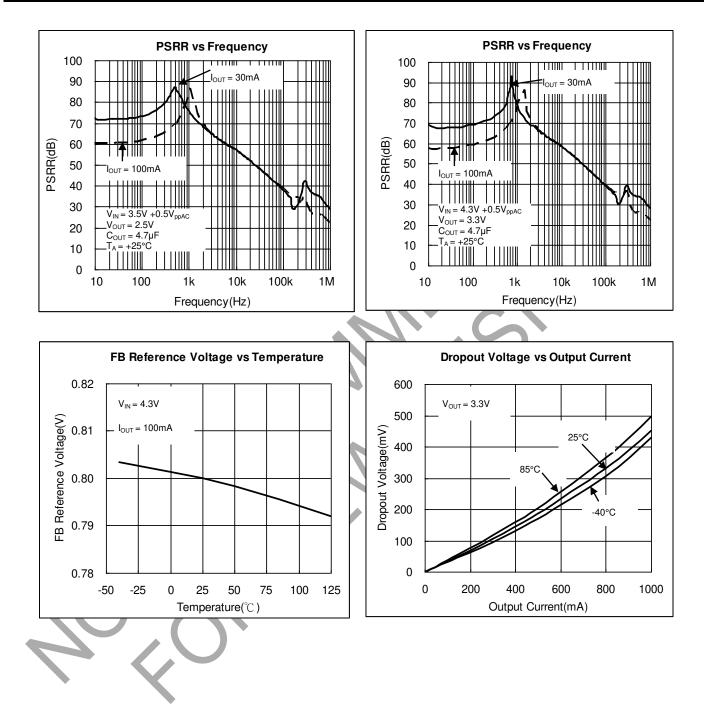




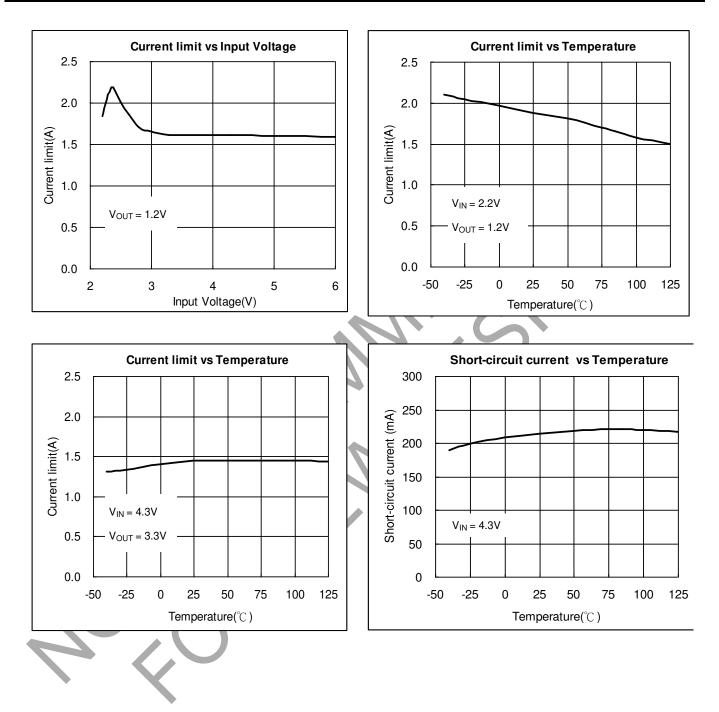




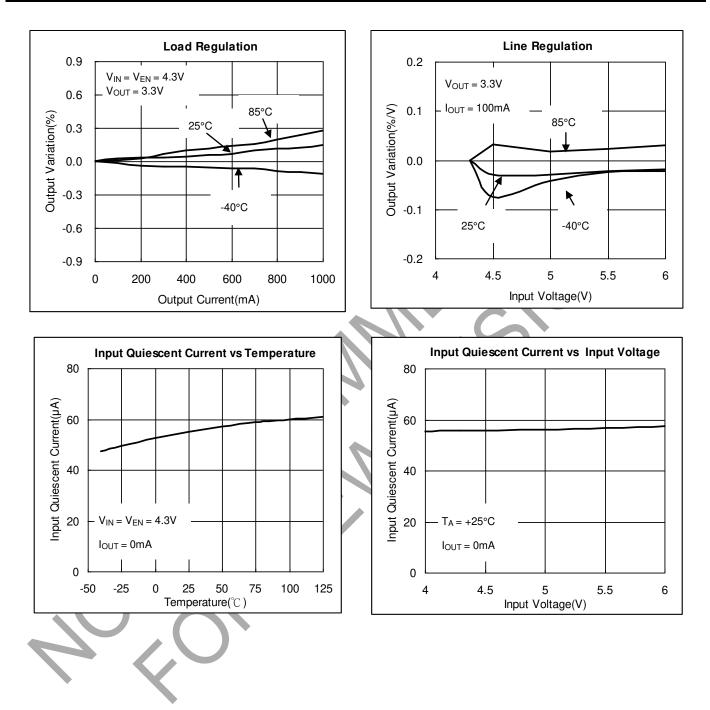














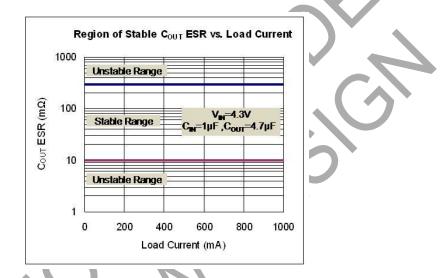
# **Application Information**

#### Input Capacitor

A 1µF ceramic capacitor is recommended between IN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and reduce noise. For PCB layout, a wide copper trace is required for both IN and GND pins. A lower ESR capacitor type allows the use of less capacitance, while a higher ESR type requires more capacitance.

#### **Output Capacitor**

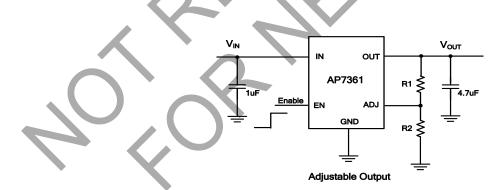
The output capacitor is required to stabilize and improve the transient response of the LDO. The AP7361 is stable with very small ceramic output capacitors. Using a ceramic capacitor value that is at least  $2.2\mu$ F with  $10m\Omega \leq ESR \leq 300m\Omega$  on the output ensures stability. Higher capacitance values help to improve line and load transient response. The output capacitance may be increased to keep low undershoot and overshoot. Output capacitor must be placed as close as possible to OUT and GND pins.



#### Adjustable Operation

external resistor divider as shown below

Adjustable operation is not available in the SOT223 TO252 and SO-8EP package. The AP7361 provides output voltage from 0.8V to 5.0V through



The output voltage is calculated by:

$$V_{OUT} = V_{REF} \left( 1 + \frac{R_1}{R_2} \right)$$

Where  $V_{REF} = 0.8V$  (the internal reference voltage)

Rearranging the equation will give the following that is used for adjusting the output to a particular voltage:

$$R_1 = R_2 \left( \frac{V_{OUT}}{V_{REF}} - 1 \right)$$

To maintain the stability of the internal reference voltage, R<sub>2</sub> need to be kept smaller than 80kΩ.



## **Application Information**

#### No Load Stability

Other than external resistor divider, no minimum load is required to keep the device stable. The device will remain stable and regulated in no load condition.

#### **ON/OFF Input Operation**

The ON/OFF feature is not available in the SOT223 and TO252 package.

The AP7361 is turned on by setting the EN pin high, and is turned off by pulling it low. If this feature is not used, the EN pin should be tied to IN pin to keep the regulator output on at all time. To ensure proper operation, the signal source used to drive the EN pin must be able to swing above and below the specified turn-on/off voltage thresholds listed in the Electrical Characteristics section under V<sub>IL</sub> and V<sub>IH</sub>.

#### **Current Limit Protection**

When output current at OUT pin is higher than current limit threshold, the current limit protection will be triggered and clamp the output current to prevent overcurrent and to protect the regulator from damage due to overheating.

#### **Short-Circuit Protection**

When OUT pin is short-circuit to GND, short circuit protection will be triggered and clamp the output current to approximately 200mA. Full current is restored when the output voltage exceeds 15% of Vout. This feature protects the regulator from overcurrent and damage due to overheating.

#### **Thermal Shutdown Protection**

Thermal protection disables the output when the junction temperature rises to approximately +150°C, allowing the device to cool down. When the junction temperature reduces to approximately +130°C the output circuitry is enabled again. Depending on power dissipation, thermal resistance, and ambient temperature, the thermal protection circuit may cycle on and off. This cycling limits the heat dissipation of the regulator, protecting it from damage due to overheating.

#### **Ultra Fast Start-up**

After enabled, the AP7361 is able to provide full power in as little as tens of microseconds, typically 200µs, without sacrificing low ground current. This feature will help load circuitry move in and out of standby mode in real time, eventually extend battery life for mobile phones and other portable devices.

#### Low Quiescent Current

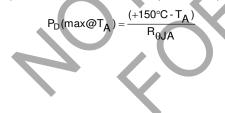
The AP7361, consuming only around 70µA for all input range, provides great power saving in portable and low power applications.

#### **Power Dissipation**

The device power dissipation and proper sizing of the thermal plane that is connected to the thermal pad is critical to avoid thermal shutdown and ensure reliable operation. Power dissipation of the device depends on input voltage and load conditions and can be calculated by:

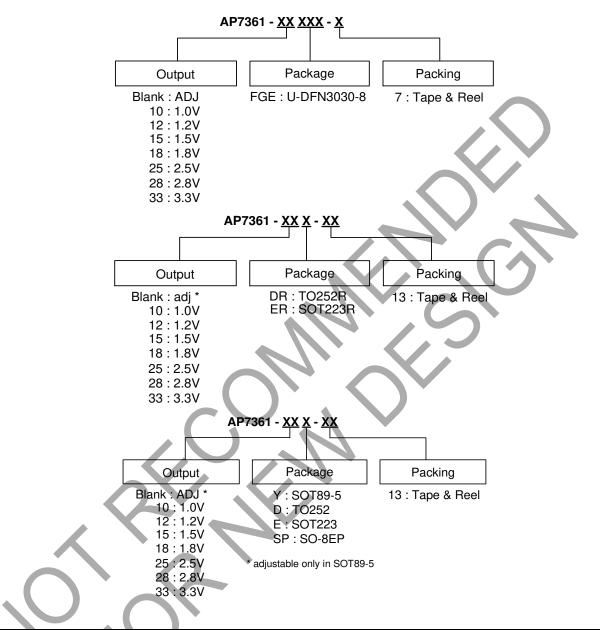
#### $\mathsf{P}_\mathsf{D} = (\mathsf{V}_\mathsf{IN} - \mathsf{V}_\mathsf{OUT}) \mathsf{X} \mathsf{I}_\mathsf{OUT}$

The maximum power dissipation, handled by the device, depends on the maximum junction to ambient thermal resistance, maximum ambient temperature, and maximum device junction temperature, which can be calculated by the equation in the following:





## **Ordering Information**



Part Number	Package Code	ckage Code Packaging	7"/13" Tape	and Reel
Part Nulliber	Fackage Code	Packaging	Quantity	Part Number Suffix
AP7361-XXFGE-7	FGE	U-DFN3030-8	3,000/Tape & Reel	-7
AP7361-XXY-13	Y	SOT89-5	2,500/Tape & Reel	-13
AP7361-XXD-13	D	TO252	2,500/Tape & Reel	-13
AP7361-XXDR-13	DR	TO252R	2,500/Tape & Real	-13
AP7361-XXE-13	E	SOT223	2,500/Tape & Reel	-13
AP7361-XXER-13	ER	SOT223R	2,500/Tape & Reel	-13
AP7361-XXSP-13	SP	SO-8EP	2,500/Tape & Reel	-13



# **Marking Information**

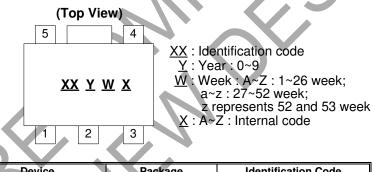
#### (1) U-DFN3030-8



- $\underline{X}$  : A~Z : Internal code

Identification Code	Package	Device
РА	U-DFN3030-8	AP7361ADJ
РВ	U-DFN3030-8	AP7361-10
PC	U-DFN3030-8	AP7361-12
PD	U-DFN3030-8	AP7361-15
PE	U-DFN3030-8	AP7361-18
PF	U-DFN3030-8	AP7361-25
PG	U-DFN3030-8	AP7361-28
PH	U-DFN3030-8	AP7361-33

#### (2) SOT89-5



•	Device	Package	Identification Code
	AP7361ADJ	SOT89-5	PA
	AP7361-10	SOT89-5	PB
	AP7361-12	SOT89-5	PC
$\frown$	AP7361-15	SOT89-5	PD
	AP7361-18	SOT89-5	PE
	AP7361-25	SOT89-5	PF
	AP7361-28	SOT89-5	PG
	AP7361-33	SOT89-5	PH
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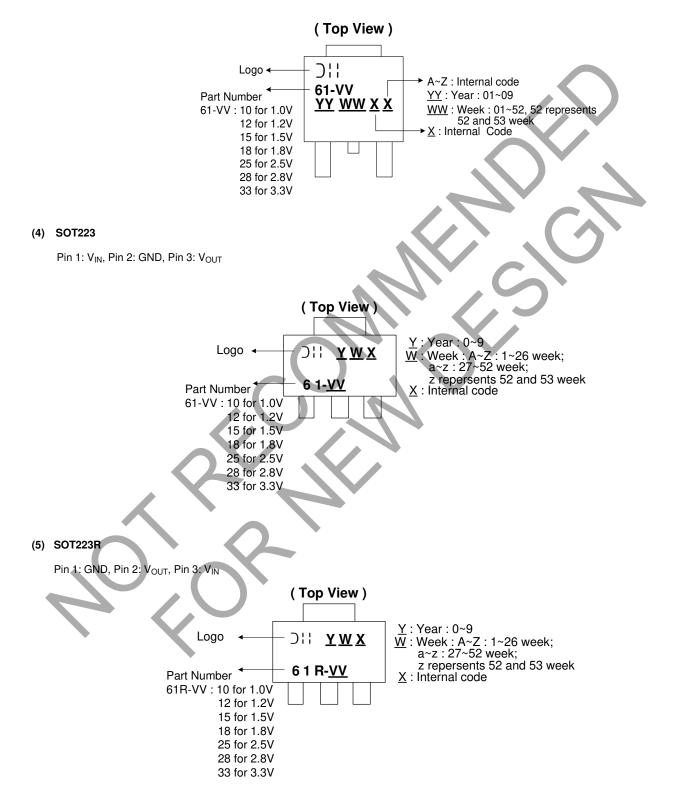
AP7361



## Marking Information (cont.)

#### (3) TO252

Pin 1: VIN, Pin 2: GND, Pin 3: VOUT

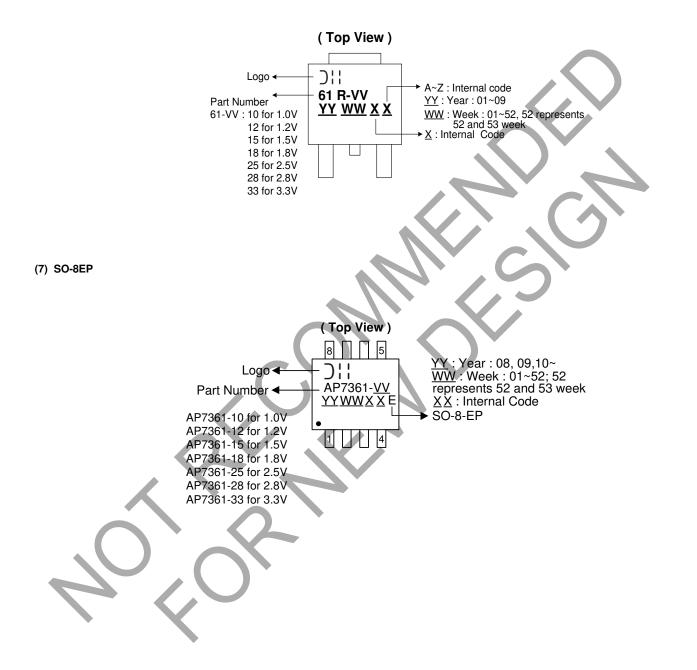




## Marking Information (cont.)

#### (6) TO252-R

Pin 1: GND, Pin 2:  $V_{OUT}$ , Pin 3:  $V_{IN}$ 

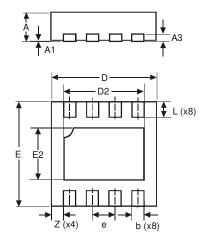




# Package Outline Dimensions (All dimensions in mm.)

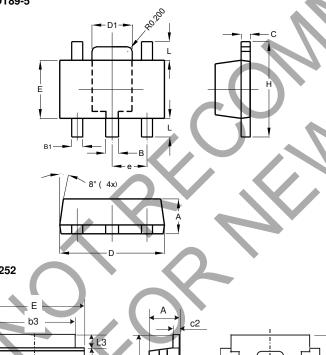
Please see http://www.diodes.com/package-outlines.html for the latest version.

#### (1): U-DFN3030-8



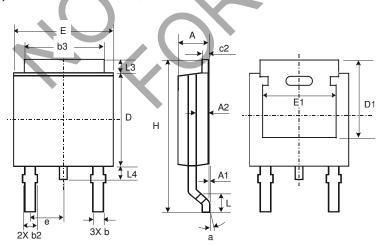
	U-DFN Ty			
Dim	Min	Max	Тур	
Α	0.57	0.63	0.60	
A1	0	0.05	0.02	
A3	-	-	0.15	
b	0.20	0.30	0.25	
D	2.95	3.05	3.00	
D2	2.15	2.35	2.25	
Е	2.95	3.05	3.00	•
е	-	-	0.65	
E2	1.40	1.60	1.50	
L	0.30	0.60	0.45	
Z	_	-	0.40	
All I	Dimens	n mm		

(2): SOT89-5



SOT89-5						
Dim	Min	Max	Тур			
Α	1.40	1.60	1.50			
В	0.50	0.62	0.56			
B1	0.44	0.54	0.48			
c	0.35	0.43	0.38			
D	4.40	4.60	4.50			
D1	1.62	1.83	1.733			
Е	2.40	2.60	2.50			
е	-	-	1.50			
H	3.95	4.25	4.10			
L	0.65	0.95	0.80			
All	All Dimensions in mm					

(3): TO252



TO252						
Dim	Min	Max	Тур			
Α	2.19	2.39	2.29			
A1	0.00	0.13	0.08			
A2	0.97	1.17	1.07			
q	0.64	0.88	0.783			
b2	0.76	1.14	0.95			
b3	5.21	5.46	5.33			
c2	0.45	0.58	0.531			
D	6.00	6.20	6.10			
D1	5.21	-	-			
е	-	-	2.286			
Е	6.45	6.70	6.58			
E1	4.32	-	-			
Н	9.40	10.41	9.91			
L	1.40	1.78	1.59			
L3	0.88	1.27	1.08			
L4	0.64	1.02	0.83			
а	0°	10°	-			
All	Dimen	sions i	n mm			



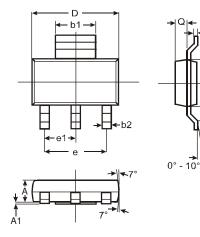
Package Outline Dimensions (cont.) (All dimensions in mm.)

Please see http://www.diodes.com/package-outlines.html for the latest version.

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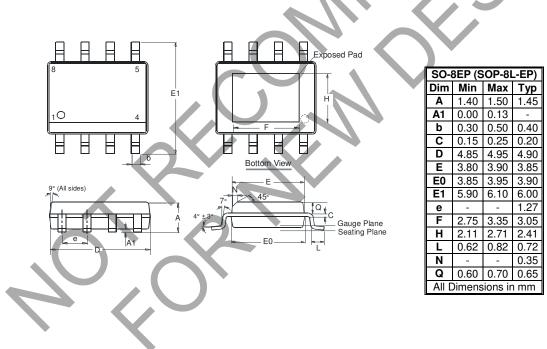
Ė E1

#### (4): SOT223 and SOT223R



	SOT223					
Dim	Min	Max	Тур			
Α	1.55	1.65	1.60			
A1	0.010	0.15	0.05			
b1	2.90	3.10	3.00			
b2	0.60	0.80	0.70			
С	0.20	0.30	0.25			
D	6.45	6.55	6.50			
Е	3.45	3.55	3.50	ĺ		
E1	6.90	7.10	7.00			
e	-		4.60			
e1			2.30			
L	0.85	1.05	0.95			
Q	0.84	0.94	0.89			
AILT	All Dimensions in mm					

(5): SO-8EP

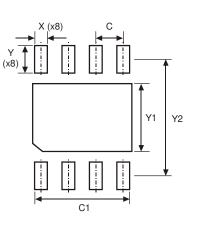


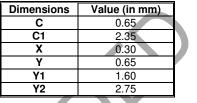


# Suggested Pad Layout

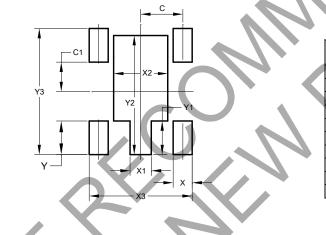
Please see http://www.diodes.com/package-outlines.html for the latest version.

#### (1): U-DFN3030-8



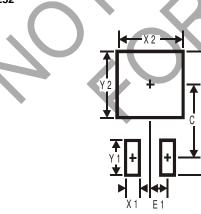


(2): SOT89-5



Dimensions	Value
Dimensions	(in mm)
C	1.500
C1	1.050
Х	0.680
X1	0.760
× X2	1.930
X3	3.680
Y	1.200
Y1	1.200
Y2	4.250
Y3	4.500

(3): TO252



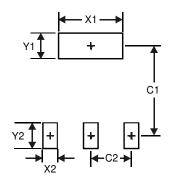
Dimensions	Value (in mm)
Z	11.6
X1	1.5
X2	7.0
Y1	2.5
Y2	7.0
С	6.9
E1	2.3



# Suggested Pad Layout (cont.)

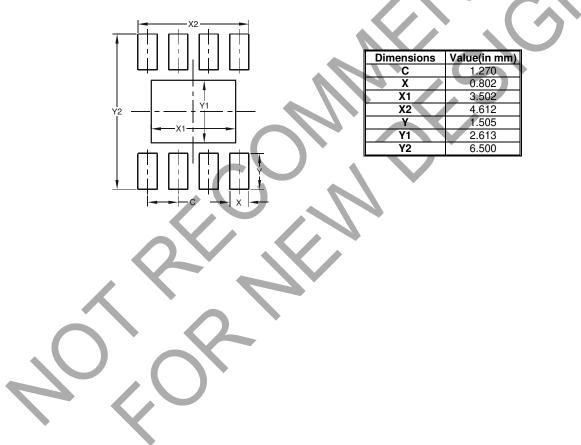
Please see http://www.diodes.com/package-outlines.html for the latest version.

#### (4): SOT223 and SOT223R



3.3 1.2 1.6	
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